

U.S. Patent Application Serial No. 10/777,039
Amendment filed February 24, 2005
Supplemental Amendment to OA dated November 4, 2004

REMARKS

As indicated above, this is a Supplement to the Response filed on February 4, 2005.

It is believed that this Supplement and the Response filed on February 4, 2005 are fully responsive to the Office Action dated November 4, 2004.

Claims 1 - 4 remain in this application. Claim 1 has been amended and claim 4 has been added.

The applicants respectfully acknowledge, with appreciation, Examiner Cathy F. Lam's taking the time to conduct a telephone interview with the applicants' undersigned representative on February 15, 2005. The undersigned also thanks Examiner Lam for the courtesy extended to him during the telephone conference.

During such telephone conference, the applicants proposed amending independent claim 1 so as to more particularly highlight the claimed copper-cobalt-nickel alloy (of the claimed alloy fine roughening particle layer) with contents of cobalt and nickel equal to or greater than that of copper

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by reciting the specific amount ratio of copper:cobalt:nickel. Accordingly, claim 1 now more particularly recites that the claimed alloy fine roughening particle layer is:

comprised of a copper-cobalt-nickel alloy with contents of cobalt and nickel equal to or greater than that of copper, wherein the amount ratio of copper-cobalt-nickel is 1 : 1.2 to 2.2 : 1.0 to 2.0.

In addition, it was contended during such interview that the copper-cobalt-nickel alloy of the alloy fine roughening particle layer is formed on a side of copper foil, the copper foil being bonded to a substrate. The Examiner was thereafter referred to the support found in line 18, page 12 through line 8, page 13 of the applicants' specification.

Moreover, it was presented to the Examiner that claim 4 will be added so as to include the limitations of independent claim 1, as originally filed, with the following additional limitations: "the copper foil being bonded to a substrate."

The Examiner thereafter suggested that such proposed claim amendments and comments be formally filed. Accordingly, the applicants herein submit the proposed claim amendments for the Examiner's consideration.

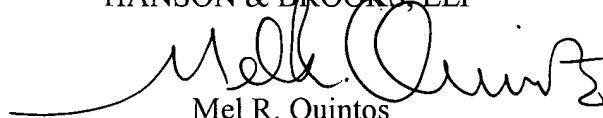
U.S. Patent Application Serial No. 10/777,039
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It is submitted that such claim amendments distinguish over the cited prior art references, singly or in combination.

If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact the applicants' undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, the applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper to Deposit Account No. 01-2340.

Respectfully submitted,
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